

Welcome to **E-XFL.COM** 

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4024lqi-s403t



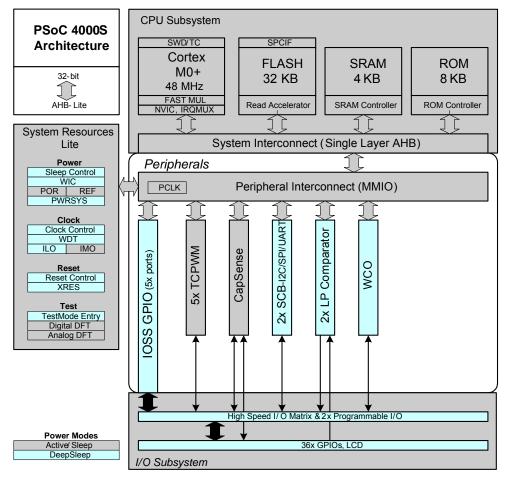


Figure 1. Block Diagram

PSoC 4000S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4000S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4000S family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4000S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4000S allows the customer to make.



#### Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the set timeout occurs. The watchdog reset is recorded in a Reset Cause register, which is firmware readable.

#### Reset

The PSoC 4000S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

#### Voltage Reference

The PSoC 4000S reference system generates all internally required references. A 1.2-V voltage reference is provided for the comparator. The IDACs are based on a ±5% reference.

#### **Analog Blocks**

#### Low-power Comparators (LPC)

The PSoC 4000S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

#### Current DACs

The PSoC 4000S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

#### Analog Multiplexed Buses

The PSoC 4000S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

#### **Programmable Digital Blocks**

The programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

#### **Fixed Function Digital**

#### Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4000S.

#### Serial Communication Block (SCB)

The PSoC 4000S has two serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

**I<sup>2</sup>C Mode**: The hardware I<sup>2</sup>C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also supports EZI2C that creates a mailbox address range in the memory of the PSoC 4000S and effectively reduces I<sup>2</sup>C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I<sup>2</sup>C peripheral is compatible with the I<sup>2</sup>C Standard-mode and Fast-mode devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4000S is not completely compliant with the I<sup>2</sup>C spec in the following respect:

■ GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.

**UART Mode**: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode**: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.



Table 1. PSoC 4000S Pin List (continued)

48	-TQFP	32	2-QFN	2	4-QFN	2	5-CSP		40-QFN
Pin	Name								
17	P3.4							14	P3.4
18	P3.5							15	P3.5
19	P3.6							16	P3.6
20	P3.7							17	P3.7
21	VDDD								
22	P4.0	13	P4.0	9	P4.0	E3	P4.0	18	P4.0
23	P4.1	14	P4.1	10	P4.1	D2	P4.1	19	P4.1
24	P4.2	15	P4.2	11	P4.2	E2	P4.2	20	P4.2
25	P4.3	16	P4.3	12	P4.3	E1	P4.3	21	P4.3

#### Descriptions of the Pin functions are as follows:

VDDD: Power supply for the digital section.

VDDA: Power supply for the analog section.

VSSD, VSSA: Ground pins for the digital and analog sections respectively.

VCCD: Regulated digital supply (1.8 V ±5%)

VDD: Power supply to all sections of the chip

VSS: Ground for all sections of the chip

#### **Alternate Pin Functions**

Each port pin can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

Port/ Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]		scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]		scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						
P0.4	wco.wco_in			scb[1].uart_rx:0		scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0		scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0			scb[1].spi_clk:1
P0.7				scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0			tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1			tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2			tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]		scb[0].spi_clk:1
P1.3			tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]		scb[0].spi_select0:1
P1.4							scb[0].spi_select1:1
P1.5							scb[0].spi_select2:1

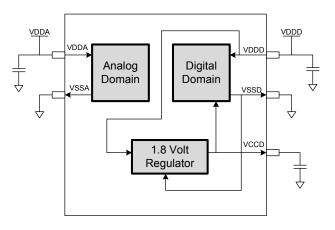
Document Number: 002-00123 Rev. \*J Page 8 of 35



#### **Power**

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4000S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the  $V_{DD}$  input.

Figure 3. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is  $1.8 \text{ V} \pm 5\%$  (externally regulated; 1.71 to 1.89, internal regulator bypassed).

#### Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4000S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4000S supplies the internal logic and its output is connected to the  $V_{CCD}$  pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1  $\mu F;\, X5R$  ceramic or better) and must not be connected to anything else.

#### Mode 2: 1.8 V ±5% External Supply

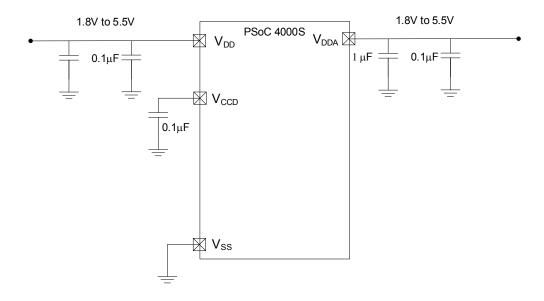
In this mode, the PSoC 4000S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- $\mu$ F range, in parallel with a smaller capacitor (0.1  $\mu$ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 4. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example





## **Development Support**

The PSoC 4000S family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

#### **Documentation**

A suite of documentation supports the PSoC 4000S family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

**Software User Guide**: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

**Component Datasheets**: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

**Application Notes**: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

**Technical Reference Manual**: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers. The TRM is available in the Documentation section at www.cypress.com/psoc4.

#### Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

#### Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4000S family is part of a development tool ecosystem. Visit us at <a href="https://www.cypress.com/go/psoccreator">www.cypress.com/go/psoccreator</a> for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.



## **Electrical Specifications**

## **Absolute Maximum Ratings**

Table 2. Absolute Maximum Ratings<sup>[1]</sup>

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID1	V <sub>DDD_ABS</sub>	Digital supply relative to V <sub>SS</sub>	-0.5	_	6		_
SID2	V <sub>CCD_ABS</sub>	Direct digital core voltage input relative to V <sub>SS</sub>	-0.5	-	1.95	V	_
SID3	V <sub>GPIO_ABS</sub>	GPIO voltage	-0.5	_	V <sub>DD</sub> +0.5	†	_
SID4	I <sub>GPIO_ABS</sub>	Maximum current per GPIO	-25	_	25		_
SID5	I <sub>GPIO_injection</sub>	GPIO injection current, Max for $V_{IH} > V_{DDD}$ , and Min for $V_{IL} < V_{SS}$	-0.5	-	0.5	mA	Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	-	-	V	_
BID45	ESD_CDM	Electrostatic discharge charged device model	500	-	_	]	_
BID46	LU	Pin current for latch-up	-140	_	140	mA	_

## **Device Level Specifications**

All specifications are valid for –40 °C  $\leq$  T<sub>A</sub>  $\leq$  85 °C and T<sub>J</sub>  $\leq$  100 °C, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

#### Table 3. DC Specifications

Typical values measured at  $V_{DD}$  = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions			
SID53	$V_{DD}$	Power supply input voltage	1.8	-	5.5		Internally regulated supply			
SID255	$V_{DD}$	Power supply input voltage (V <sub>CCD</sub> = V <sub>DD</sub> = V <sub>DDA</sub> )	1.71	-	1.89	V	Internally unregulated supply			
SID54	V <sub>CCD</sub>	Output voltage (for core logic)	_	1.8	_		_			
SID55	C <sub>EFC</sub>	External regulator voltage bypass	_	0.1	_	E	X5R ceramic or better			
SID56	C <sub>EXC</sub>	Power supply bypass capacitor	_	1	_	μF	X5R ceramic or better			
Active Mode, \	V <sub>DD</sub> = 1.8 V to 5.	5 V. Typical values measured at VDD =	: 3.3 V and	25 °C.						
SID10	I <sub>DD5</sub>	Execute from flash; CPU at 6 MHz	_	1.2	2.0		_			
SID16	I <sub>DD8</sub>	Execute from flash; CPU at 24 MHz	_	2.4	4.0	mA	_			
SID19	I <sub>DD11</sub>	Execute from flash; CPU at 48 MHz	_	4.6	5.9		_			
Sleep Mode, V	Sleep Mode, VDDD = 1.8 V to 5.5 V (Regulator on)									
SID22	I <sub>DD17</sub>	I <sup>2</sup> C wakeup WDT, and Comparators on	_	1.1	1.6	mA	6 MHz			
SID25	I <sub>DD20</sub>	I <sup>2</sup> C wakeup, WDT, and Comparators on	_	1.4	1.9		12 MHz			

#### Note

Document Number: 002-00123 Rev. \*J Page 12 of 35

Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended
periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature
Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.



# **Analog Peripherals**

## Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID84	V <sub>OFFSET1</sub>	Input offset voltage, Factory trim	_	_	±10		_
SID85	V <sub>OFFSET2</sub>	Input offset voltage, Custom trim	_	_	±4	mV	_
SID86	V <sub>HYST</sub>	Hysteresis when enabled	_	10	35		_
SID87	V <sub>ICM1</sub>	Input common mode voltage in normal mode	0	_	V <sub>DDD</sub> -0.1		Modes 1 and 2
SID247	V <sub>ICM2</sub>	Input common mode voltage in low power mode	0	_	$V_{DDD}$	V	_
SID247A	V <sub>ICM3</sub>	Input common mode voltage in ultra low power mode	0	_	V <sub>DDD</sub> -1.15		V <sub>DDD</sub> ≥ 2.2 V at -40 °C
SID88	C <sub>MRR</sub>	Common mode rejection ratio	50	_	-	dB	V <sub>DDD</sub> ≥ 2.7V
SID88A	C <sub>MRR</sub>	Common mode rejection ratio	42	_	-	uБ	V <sub>DDD</sub> ≤ 2.7V
SID89	I <sub>CMP1</sub>	Block current, normal mode	_	_	400		_
SID248	I <sub>CMP2</sub>	Block current, low power mode	_	_	100	μA	_
SID259	I <sub>CMP3</sub>	Block current in ultra low-power mode	_	6	28	μ, ,	V <sub>DDD</sub> ≥ 2.2 V at -40 °C
SID90	Z <sub>CMP</sub>	DC Input impedance of comparator	35	_	_	МΩ	-

## Table 10. Comparator AC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID91	TRESP1	Response time, normal mode, 50 mV overdrive	-	38	110	ns	_
SID258	TRESP2	Response time, low power mode, 50 mV overdrive	-	70	200	115	_
SID92	TRESP3	Response time, ultra-low power mode, 200 mV overdrive	_	2.3	15	μs	V <sub>DDD</sub> ≥ 2.2 V at -40 °C

Document Number: 002-00123 Rev. \*J Page 16 of 35



CSD

Table 11. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	_	_	±50	mV	V <sub>DD</sub> > 2 V (with ripple), 25 °C T <sub>A</sub> , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	-	-	±25	mV	$V_{DD}$ > 1.75V (with ripple), 25 °C T <sub>A</sub> , Parasitic Capaci tance (C <sub>P</sub> ) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	-	_	4000	μA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	$V_{REF}$	Voltage reference for CSD and Comparator	0.6	1.2	V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		V <sub>DDA</sub> - 0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	-	-	1750	μΑ	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	-	-	1750	μΑ	
SID308	VCSD	Voltage range of operation	1.71	-	5.5	V	1.8 V ±5% or 1.8 V to 5.5 \
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	-	V <sub>DDA</sub> -0.6	V	V <sub>DDA</sub> - 0.06 or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	-1	-	1	LSB	
SID310	IDAC1INL	INL	-2	-	2	LSB	INL is $\pm 5.5$ LSB for $V_{DDA} < 2$ V
SID311	IDAC2DNL	DNL	<b>–</b> 1	_	1	LSB	
SID312	IDAC2INL	INL	-2	_	2	LSB	INL is ±5.5 LSB for V <sub>DDA</sub> < 2 V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	_	-	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V <sub>DDA</sub> > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	-	5.4	μA	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1(7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1(7 bits) in high range	275	_	330	μA	LSB = 2.4-μA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	-	10.5	μA	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	-	82	μA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	-	660	μA	LSB = 4.8-μA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	_	5.4	μA	LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	-	330	μA	LSB = 2.4-µA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	_	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	_	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	_	660	μA	LSB = 4.8-μA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	-	10.5	μA	LSB = 37.5-nA typ.

Document Number: 002-00123 Rev. \*J



Table 11. CSD and IDAC Specifications (continued)

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	_	82	μA	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	_	660	μA	LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	-	-	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	-	_	±10	%	
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	-	-	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	-	-	5.6	LSB	LSB = 300-nA typ.
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	-	-	6.8	LSB	LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	-	-	10	μs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	_	-	10	μs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	-	2.2	_	nF	5-V rating, X7R or NP0 cap.

Table 12. 10-bit CapSense ADC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SIDA94	A_RES	Resolution	_	_	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	_	-	16		Defined by AMUX Bus.
SIDA97	A-MONO	Monotonicity	-	_	_	Yes	
SIDA98	A_GAINERR	Gain error	-	_	±2	%	In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capac- itance of 10 µF
SIDA99	A_OFFSET	Input offset voltage	-	-	3	mV	In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capac- itance of 10 µF
SIDA100	A_ISAR	Current consumption	-	_	0.25	mA	
SIDA101	A_VINS	Input voltage range - single ended	$V_{SSA}$	-	$V_{DDA}$	V	
SIDA103	A_INRES	Input resistance	-	2.2	_	ΚΩ	
SIDA104	A_INCAP	Input capacitance	-	20	_	pF	
SIDA106	A_PSRR	Power supply rejection ratio	-	60	-	dB	In V <sub>REF</sub> (2.4 V) mode with V <sub>DDA</sub> bypass capac- itance of 10 µF
SIDA107	A_TACQ	Sample acquisition time	-	1	_	μs	
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	-	_	21.3	μs	Does not include acquisition time. Equivalent to 44.8 ksps including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	-	-	85.3	μs	Does not include acquisition time. Equivalent to 11.6 ksps including acquisition time.

Document Number: 002-00123 Rev. \*J Page 18 of 35



 Table 12. 10-bit CapSense ADC Specifications (continued)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SIDA109	A_SND	Signal-to-noise and Distortion ratio (SINAD)	-	61	-	dB	With 10-Hz input sine wave, external 2.4-V reference, V <sub>REF</sub> (2.4 V) mode
SIDA110	A_BW	Input bandwidth without aliasing	_	_	22.4	kHz	8-bit resolution
SIDA111	A_INL	Integral Non Linearity. 1 ksps	_	_	2	LSB	V <sub>REF</sub> = 2.4 V or greater
SIDA112	A_DNL	Differential Non Linearity. 1 ksps	_	_	1	LSB	

## **Digital Peripherals**

Timer Counter Pulse-Width Modulator (TCPWM)

**Table 13. TCPWM Specifications** 

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.TCPWM.1	ITCPWM1	Block current consumption at 3 MHz	-	_	45		All modes (TCPWM)
SID.TCPWM.2	ITCPWM2	Block current consumption at 12 MHz	-	_	155	μΑ	All modes (TCPWM)
SID.TCPWM.2A	ITCPWM3	Block current consumption at 48 MHz	-	_	650		All modes (TCPWM)
SID.TCPWM.3	TCPWM <sub>FREQ</sub>	Operating frequency	-	-	Fc	MHz	Fc max = CLK_SYS Maximum = 48 MHz
SID.TCPWM.4	TPWM <sub>ENEXT</sub>	Input trigger pulse width	2/Fc	_	-		For all trigger events <sup>[6]</sup>
SID.TCPWM.5	TPWM <sub>EXT</sub>	Output trigger pulse widths	2/Fc	1	ı		Minimum possible width of Overflow, Underflow, and CC (Counter equals Compare value) outputs
SID.TCPWM.5A	TC <sub>RES</sub>	Resolution of counter	1/Fc	-	_	ns	Minimum time between successive counts
SID.TCPWM.5B	PWM <sub>RES</sub>	PWM resolution	1/Fc	-	-		Minimum pulse width of PWM Output
SID.TCPWM.5C	Q <sub>RES</sub>	Quadrature inputs resolution	1/Fc	_	-		Minimum pulse width between Quadrature phase inputs

Document Number: 002-00123 Rev. \*J Page 19 of 35

Note
6. Trigger events can be Stop, Start, Reload, Count, Capture, or Kill depending on which mode of operation is selected.



# Table 18. UART DC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbps	_	_	55	μΑ	_
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbps	-	_	312	μA	_

# Table 19. UART AC Specifications $^{[8]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	1	ı	1	Mbps	-

# Table 20. LCD Direct Drive DC Specifications $^{[8]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID154	I <sub>LCDLOW</sub>	Operating current in low power mode	ı	5	-	μA	16 × 4 small segment disp. at 50 Hz
SID155	C <sub>LCDCAP</sub>	LCD capacitance per segment/common driver	_	500	5000	pF	-
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	-	20	-	mV	-
SID157	I <sub>LCDOP1</sub>	LCD system operating current Vbias = 5 V	-	2	-	mΛ	$32 \times 4$ segments. 50 Hz. 25 °C
SID158	I <sub>LCDOP2</sub>	LCD system operating current Vbias = 3.3 V	_	2	_	mA	32 × 4 segments. 50 Hz. 25 °C

# Table 21. LCD Direct Drive AC Specifications<sup>[8]</sup>

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	-

8. Guaranteed by characterization.



#### Memory

#### Table 22. Flash DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID173	$V_{PE}$	Erase and program voltage	1.71	ı	5.5	V	_

## Table 23. Flash AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID174	T <sub>ROWWRITE</sub> <sup>[9]</sup>	Row (block) write time (erase and program)	-	_	20		Row (block) = 128 bytes
SID175	T <sub>ROWERASE</sub> <sup>[9]</sup>	Row erase time	-	-	16	ms	_
SID176	T <sub>ROWPROGRAM</sub> <sup>[9]</sup>	Row program time after erase	-	_	4		-
SID178	T <sub>BULKERASE</sub> <sup>[9]</sup>	Bulk erase time (32 KB)	-	-	35		_
SID180 <sup>[10]</sup>	T <sub>DEVPROG</sub> <sup>[9]</sup>	Total device program time	_	-	7	Seconds	-
SID181 <sup>[10]</sup>	F <sub>END</sub>	Flash endurance	100 K	-	_	Cycles	-
SID182 <sup>[10]</sup>	F <sub>RET</sub>	Flash retention. $T_A \le 55$ °C, 100 K P/E cycles	20	-	_	- Years	_
SID182A <sup>[10]</sup>	_	Flash retention. $T_A \le 85$ °C, 10 K P/E cycles	10	-	_	Tears	_
SID256	TWS48	Number of Wait states at 48 MHz	2	-	_		CPU execution from Flash
SID257	TWS24	Number of Wait states at 24 MHz	1	_	_		CPU execution from Flash

## **System Resources**

Power-on Reset (POR)

## Table 24. Power On Reset (PRES)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID.CLK#6	SR_POWER_UP	Power supply slew rate	1	1	67	V/ms	At power-up
SID185 <sup>[10]</sup>	V <sub>RISEIPOR</sub>	Rising trip voltage	0.80	1	1.5	V	_
SID186 <sup>[10]</sup>	V <sub>FALLIPOR</sub>	Falling trip voltage	0.70	-	1.4		_

## Table 25. Brown-out Detect (BOD) for $V_{\mbox{\scriptsize CCD}}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID190 <sup>[10]</sup>	V <sub>FALLPPOR</sub>	BOD trip voltage in active and sleep modes	1.48	1	1.62	V	-
SID192 <sup>[10]</sup>	V <sub>FALLDPSLP</sub>	BOD trip voltage in Deep Sleep	1.11	ı	1.5		-

Document Number: 002-00123 Rev. \*J Page 22 of 35

Notes

9. It can take as much as 20 milliseconds to write to Flash. During this time the device should not be Reset, or Flash operations will be interrupted and cannot be relied on to have completed. Reset sources include the XRES pin, software resets, CPU lockup states and privilege violations, improper power supply levels, and watchdogs. Make certain that these are not inadvertently activated.



#### SWD Interface

## **Table 26. SWD Interface Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID213	F_SWDCLK1	$3.3~V \leq V_{DD} \leq 5.5~V$	_	I	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$	_	ı	7		SWDCLK ≤ 1/3 CPU clock frequency
SID215 <sup>[11]</sup>	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	_	_		_
SID216 <sup>[11]</sup>	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	_	_	ne	_
SID217 <sup>[11]</sup>	T_SWDO_VALID	T = 1/f SWDCLK	_	_	0.5*T	ns	_
SID217A <sup>[11]</sup>	T_SWDO_HOLD	T = 1/f SWDCLK	1	_	_		_

Internal Main Oscillator

## Table 27. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID218	I <sub>IMO1</sub>	IMO operating current at 48 MHz	_	_	250	μA	-
SID219	I <sub>IMO2</sub>	IMO operating current at 24 MHz	-	-	180	μΑ	_

## Table 28. IMO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID223	F <sub>IMOTOL1</sub>	Frequency variation at 24, 32, and 48 MHz (trimmed)	_	_	±2	%	
SID226	T <sub>STARTIMO</sub>	IMO startup time	_	_	7	μs	-
SID228	T <sub>JITRMSIMO2</sub>	RMS jitter at 24 MHz	_	145	-	ps	_

Internal Low-Speed Oscillator

#### Table 29. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID231 <sup>[11]</sup>	I <sub>ILO1</sub>	ILO operating current	ı	0.3	1.05	μΑ	_

#### Table 30. ILO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID234 <sup>[11]</sup>	T <sub>STARTILO1</sub>	ILO startup time	_	-	2	ms	_
SID236 <sup>[11]</sup>	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	_
SID237	F <sub>ILOTRIM1</sub>	ILO frequency range	20	40	80	kHz	_

Document Number: 002-00123 Rev. \*J Page 23 of 35

**Note** 11. Guaranteed by characterization.



## Table 31. Watch Crystal Oscillator (WCO) Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SID398	FWCO	Crystal Frequency	-	32.768	_	kHz	
SID399	FTOL	Frequency tolerance	_	50	250	ppm	With 20-ppm crystal
SID400	ESR	Equivalent series resistance	_	50	_	kΩ	
SID401	PD	Drive Level	-	_	1	μW	
SID402	TSTART	Startup time	_	_	500	ms	
SID403	CL	Crystal Load Capacitance	6	_	12.5	pF	
SID404	C0	Crystal Shunt Capacitance	_	1.35	_	pF	
SID405	IWCO1	Operating Current (high power mode)	_	_	8	uA	
SID406	IWCO2	Operating Current (low power mode)	_	_	1	uA	

## **Table 32. External Clock Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
	•	External clock input frequency	0	_	48	MHz	-
SID306 <sup>[12]</sup>	ExtClkDuty	Duty cycle; measured at V <sub>DD/2</sub>	45	_	55	%	-

## Table 33. Block Specs

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID262 <sup>[12]</sup>	T <sub>CLKSWITCH</sub>	System clock source switching time	3	-	4	Periods	_

# Table 34. Smart I/O Pass-through Time (Delay in Bypass Mode)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SID252	_	Max delay added by Smart I/O in bypass mode	_	_	1.6	ns	

Document Number: 002-00123 Rev. \*J Page 24 of 35

**Note** 12. Guaranteed by characterization.



# **Ordering Information**

The PSoC 4000S part numbers and features are listed in the following table.

Table 35. PSoC 4000S Ordering Information

							Feat	ures						Package				
Category	MPN	Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CapSense	10-bit CSD ADC	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	WLCSP (0.35-mm pitch)	24-Pin QFN	32-Pin QFN	40-Pin QFN	48-Pin TQFP
	CY8C4024FNI-S402	24	16	2	0	0	1	0	2	5	2	8	21	~				
	CY8C4024LQI-S401	24	16	2	0	0	1	0	2	5	2	8	19		~			
	CY8C4024LQI-S402	24	16	2	0	0	1	0	2	5	2	16	27			~		
	CY8C4024LQI-S403	24	16	2	0	0	1	0	2	5	2	16	34				>	
4024	CY8C4024AZI-S403	24	16	2	0	0	1	0	2	5	2	16	36					~
4024	CY8C4024FNI-S412	24	16	2	0	1	1	0	2	5	2	8	21	~				
	CY8C4024LQI-S411	24	16	2	0	1	1	0	2	5	2	8	19		~			
	CY8C4024LQI-S412	24	16	2	0	1	1	0	2	5	2	16	27			~		
	CY8C4024LQI-S413	24	16	2	0	1	1	0	2	5	2	16	34				~	
	CY8C4024AZI-S413	24	16	2	0	1	1	0	2	5	2	16	36					~
	CY8C4025FNI-S402	24	32	4	0	0	1	0	2	5	2	8	21	~				
	CY8C4025LQI-S401	24	32	4	0	0	1	0	2	5	2	8	19		~			
	CY8C4025LQI-S402	24	32	4	0	0	1	0	2	5	2	16	27			~		
4025	CY8C4025AZI-S403	24	32	4	0	0	1	0	2	5	2	16	36					~
4023	CY8C4025FNI-S412	24	32	4	0	1	1	0	2	5	2	8	21	~				
	CY8C4025LQI-S411	24	32	4	0	1	1	0	2	5	2	8	19		~			
	CY8C4025LQI-S412	24	32	4	0	1	1	0	2	5	2	16	27			~		
	CY8C4025AZI-S413	24	32	4	0	1	1	0	2	5	2	16	36					~
	CY8C4045FNI-S412	48	32	4	0	1	1	0	2	5	2	8	21	~				
4045	CY8C4045LQI-S411	48	32	4	0	1	1	0	2	5	2	8	19		~			
4040	CY8C4045LQI-S412	48	32	4	0	1	1	0	2	5	2	16	27			~		
	CY8C4045AZI-S413	48	32	4	0	1	1	0	2	5	2	16	36					~

The nomenclature used in the preceding table is based on the following part numbering convention:

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
Α	Family	0	4000 Family
В	CPU Speed	2	24 MHz
	CPU Speed	4	48 MHz

Document Number: 002-00123 Rev. \*J Page 25 of 35



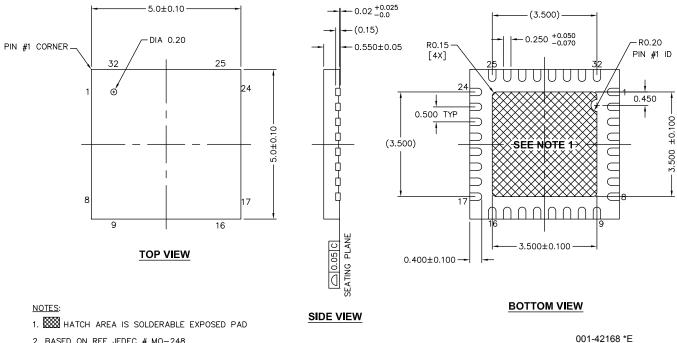
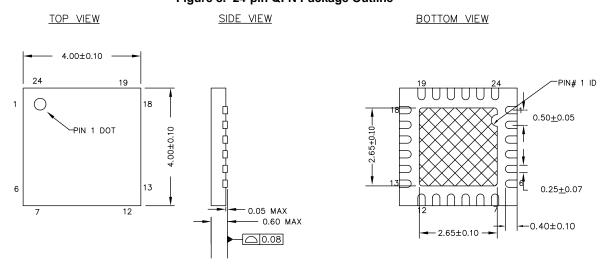


Figure 7. 32-pin QFN Package Outline

- 2. BASED ON REF JEDEC # MO-248
- 3. PACKAGE WEIGHT: 0.0388g
- 4. DIMENSIONS ARE IN MILLIMETERS

Figure 8. 24-pin QFN Package Outline



#### NOTES:

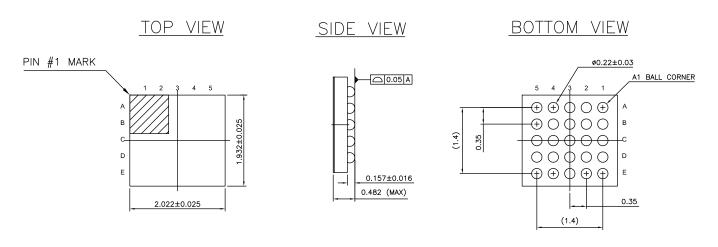
- HATCH IS SOLDERABLE EXPOSED METAL.
- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT:  $29 \pm 3 \text{ mg}$
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-13937 \*F

The center pad on the QFN package should be connected to ground (VSS) for best mechanical, thermal, and electrical performance. If not connected to ground, it should be electrically floating and not connected to any other signal.



Figure 9. 25-Ball WLCSP



ALL DIMENSIONS ARE IN MM JEDEC Publication 95; Design Guide 4.18 002-09957 \*\*



# **Acronyms**

Table 40. Acronyms Used in this Document

Acronym	Description
abus	analog local bus
ADC	analog-to-digital converter
AG	analog global
АНВ	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus
ALU	arithmetic logic unit
AMUXBUS	analog multiplexer bus
API	application programming interface
APSR	application program status register
ARM <sup>®</sup>	advanced RISC machine, a CPU architecture
ATM	automatic thump mode
BW	bandwidth
CAN	Controller Area Network, a communications protocol
CMRR	common-mode rejection ratio
CPU	central processing unit
CRC	cyclic redundancy check, an error-checking protocol
DAC	digital-to-analog converter, see also IDAC, VDAC
DFB	digital filter block
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.
DMIPS	Dhrystone million instructions per second
DMA	direct memory access, see also TD
DNL	differential nonlinearity, see also INL
DNU	do not use
DR	port write data registers
DSI	digital system interconnect
DWT	data watchpoint and trace
ECC	error correcting code
ECO	external crystal oscillator
EEPROM	electrically erasable programmable read-only memory
EMI	electromagnetic interference
EMIF	external memory interface
EOC	end of conversion
EOF	end of frame
EPSR	execution program status register
ESD	electrostatic discharge

Table 40. Acronyms Used in this Document (continued)

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I <sup>2</sup> C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
NVL	nonvolatile latch, see also WOL
opamp	operational amplifier
PAL	programmable array logic, see also PLD

Document Number: 002-00123 Rev. \*J Page 31 of 35



# **Revision History**

Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4883809	WKA	08/28/2015	New datasheet
*A	4992376	WKA	10/30/2015	Updated Pinouts. Added $V_{DDD} \ge 2.2V$ at −40 °C under Conditions for specs SID247A, SID90, SID92. Updated Table 12. Updated Ordering Information.
*B	5037826	SLAN	12/08/2015	Changed datasheet status to Preliminary
*C	5104369	WKA	01/27/2016	Added Errata. Added 25 WLCSP package details. Updated theta J <sub>A</sub> and J <sub>C</sub> values for all packages.
*D	5139206	WKA	02/16/2016	Updated copyright information at the end of the document.
*E	5173961	WKA	03/15/2016	Updated Pinouts. Updated values for SID79, BID194. SID175, and SID176. Updated CSD and IDAC Specifications. Updated 10-bit CapSense ADC Specifications.
*F	5268662	WKA	05/12/2016	Updated Alternate Pin Functions. Updated the following specs: SID310, SID312, SID313, SID314, SID314C, SID314D, SID314E, SID315, SID315C, SID315D, SID315E, SID322A, SID322B, SIDA109. Removed Errata section. Updated the Cypress logo and copyright information based on the template.
*G	5330930	WKA	07/27/2016	Updated LCD Segment Drive. Updated SID60 conditions. Updated IDD specs. Corrected package dimensions for WLCSP package and added WLCSP MSL condition. Moved datasheet status to Final.
*H	5415365	WKA	09/14/2016	Added 40-pin QFN pin and package details. Updated IDD spec values in DC Specifications.
*	5561833	WKA	01/09/2017	Changed PRGIO references to Smart I/O.
*J	5704046	GNKK	04/26/2017	Updated the Cypress logo and copyright information.

# Sales, Solutions, and Legal Information

#### Worldwide Sales and Design Support

Cypress maintains a worldwide network of offices, solution centers, manufacturer's representatives, and distributors. To find the office closest to you, visit us at Cypress Locations.

cypress.com/touch

cypress.com/wireless

cypress.com/usb

#### **Products**

Touch Sensing

**USB Controllers** 

Wireless Connectivity

ARM® Cortex® Microcontrollers cypress.com/arm Automotive cypress.com/automotive Clocks & Buffers cypress.com/clocks Interface cypress.com/interface Internet of Things cypress.com/iot Memory cypress.com/memory Microcontrollers cypress.com/mcu **PSoC** cypress.com/psoc Power Management ICs cypress.com/pmic

#### PSoC<sup>®</sup>Solutions

PSoC 1 | PSoC 3 | PSoC 4 | PSoC 5LP | PSoC 6

#### **Cypress Developer Community**

Forums | WICED IOT Forums | Projects | Video | Blogs | Training | Components

#### **Technical Support**

cypress.com/support

© Cypress Semiconductor Corporation, 2015-2017. This document is the property of Cypress Semiconductor Corporation and its subsidiaries, including Spansion LLC ("Cypress"). This document, including any software or firmware included or referenced in this document ("Software"), is owned by Cypress under the intellectual property laws and treaties of the United States and other countries worldwide. Cypress reserves all rights under such laws and treaties and does not, except as specifically stated in this paragraph, grant any license under its patents, copyrights, trademarks, or other intellectual property rights. If the Software is not accompanied by a license agreement and you do not otherwise have a written agreement with Cypress governing the use of the Software, then Cypress parally grants you a personal, non-exclusive, nontransferable license (without the right to sublicense) (1) under its copyright rights in the Software (a) for Software provided in source code form, to modify and reproduce the Software solely for use with Cypress hardware products, only internally within your organization, and (b) to distribute the Software in binary code form externally to end users (either directly or indirectly through resellers and distributors), solely for use on Cypress hardware product units, and (2) under those claims of Cypress's patents that are infringed by the Software (as provided by Cypress, unmodified) to make, use, distribute, and import the Software solely for use with Cypress hardware products. Any other use, reproduction, modification, translation, or compilation of the Software is prohibited.

TO THE EXTENT PERMITTED BY APPLICABLE LAW, CYPRESS MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARD TO THIS DOCUMENT OR ANY SOFTWARE OR ACCOMPANYING HARDWARE, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE. To the extent permitted by applicable law, Cypress reserves the right to make changes to this document without further notice. Cypress does not assume any liability arising out of the application or use of any product or circuit described in this document. Any information provided in this document, including any sample design information or programming code, is provided only for reference purposes. It is the responsibility of the user of this document to properly design, program, and test the functionality and safety of any application made of this information and any resulting product. Cypress products are not designed, intended, or authorized for use as critical components in systems designed or intended for the operation of weapons, weapons systems, nuclear installations, life-support devices or systems, other medical devices or systems (including resuscitation equipment and surgical implants), pollution control or hazardous substances management, or other teablitude of the device or system could cause personal injury, death, or property damage ("Unintended Uses"). A critical component is any component of a device or system whose failure to perform can be reasonably expected to cause the failure of the device or system, or to affect its safety or effectiveness. Cypress is not liable, in whole or in part, and you shall and hereby do release Cypress from any claim, damage, or other liability arising from or related to all Unintended Uses of Cypress products. You shall indemnify and hold Cypress harmless from and against all claims, costs, damages, and other liabilities, including claims for personal injury or death, arising from or related to any Unintended Uses of Cypress products.

Cypress, the Cypress logo, Spansion, the Spansion logo, and combinations thereof, WICED, PSoC, CapSense, EZ-USB, F-RAM, and Traveo are trademarks or registered trademarks of Cypress in the United States and other countries. For a more complete list of Cypress trademarks, visit cypress.com. Other names and brands may be claimed as property of their respective owners.

Document Number: 002-00123 Rev. \*J Revised April 26, 2017 Page 35 of 35